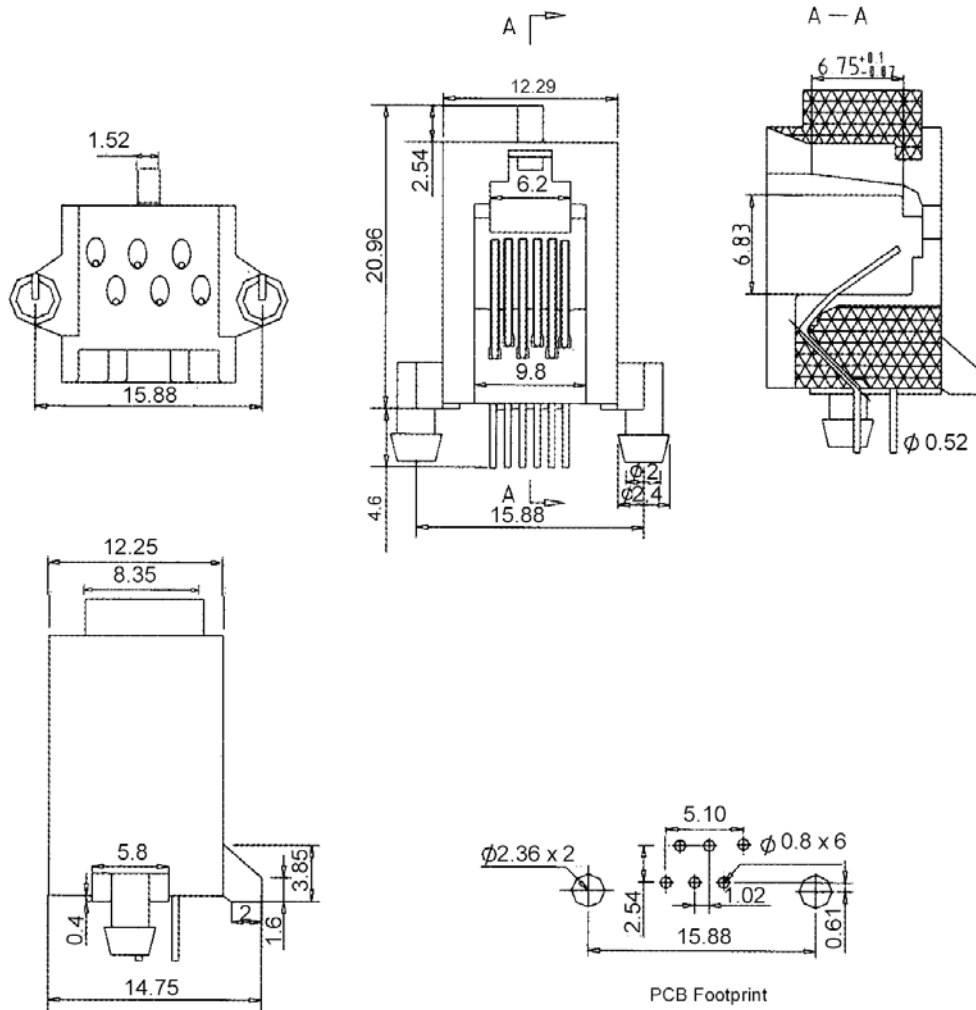


**Standard 623 profile.  
Black colour**

**P1341 PCB Socket**



Cat # P1341 6P6C PCB-mount socket

## MATERIALS

Contact: Phosphor Bronze  
 Gold plated contact area  
 Solder tails are either gold or tin plated with nickle under-plating

Housing High temperature thermoplastic, UL94V-0, Black

## RATINGS

Relative Humidity	70% ±10%RH
Operating Temperature	-40°C to 85°C
Current Rating	1.5A Max.
Voltage Rating	150V AC Max.

## ELECTRICAL

Contact Resistance *	20mΩ Max. initial; 30mΩ Max final (See Fig1)
Dielectric Withstanding Voltage **	No discharge or flashover shall occur. Current leakage 0.5mA Max.
Insulation Resistance ***	500 MΩ initial; 200MΩ final

- \* Open circuit at 20mV Max.; 100mA Max.
- \*\* Test between adjacent contacts of an unmated connector @ 1KVrms at 60Hz for 1 minute.
- \*\*\* Test between adjacent contacts of an unmated connector @ 500V DC for 1 minute.

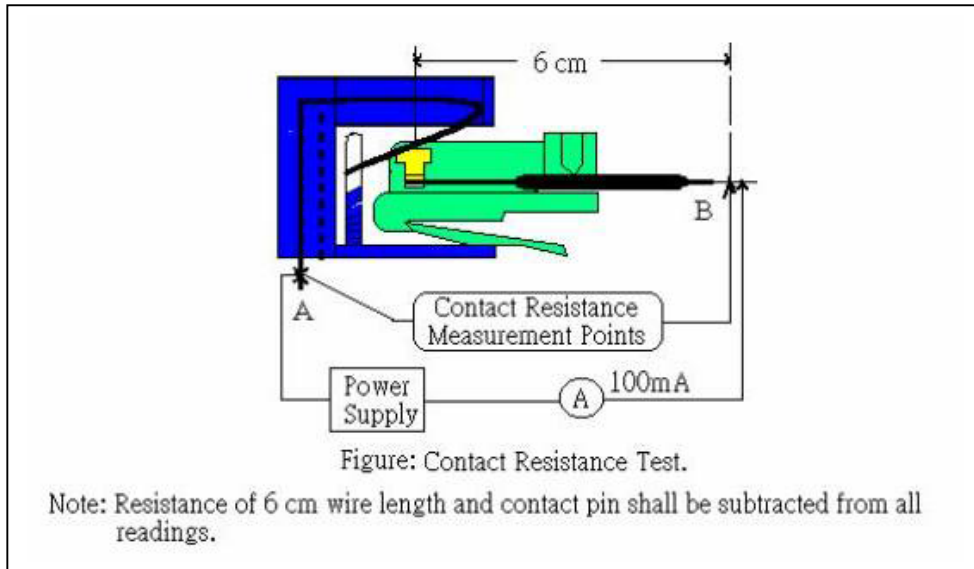


Fig 1

Cat # P1341 6P6C PCB-mount socket

## MECHANICAL

Contact Normal Force	0.1kgf Min.
Durability *	Shall show no physical damage and meet the requirements of additional tests as shown in Fig 2.
Mating Force **	2 contacts 1.6kgf Max 4 contacts 1.8kgf Max. 6 contacts 2.1kgf Max. 8 contacts 2.3kgf Max. 10 contacts 2.5kgf Max..

\* Mate and un-mate for 750 cycles with an operation speed of 25mm/min

\*\* Operation speed 25mm/min

## ENVIRONMENTAL

Humidity Test *	Shall show no physical damage and meet the requirements of additional tests as shown in Fig 2
Temperature Life **	Shall show no physical damage and meet the requirements of additional tests as shown in Fig 2
Salt Spray ***	No detrimental corrosion allowed in the contact area and the base metal shall not be exposed.
Solderability ****	The inspected area of each lead must have 95% minimum solder coverage

\* Temperature of 40°C ±2°C and relative humidity of 90% to 95% for 96 hours.

\*\* Temperature of 65°C ±2°C for 96 hours.

\*\*\* Subject mated connectors to 35°C ±2°C and 5% ±1% salt condition for 48 hours. After testing, rinse the sample with water and recondition to room temperature for 1 hour..

\*\*\*\* Solder pot temperature 245°C ± 5°C. Solder immersion time 5 ± 0.5 sec..

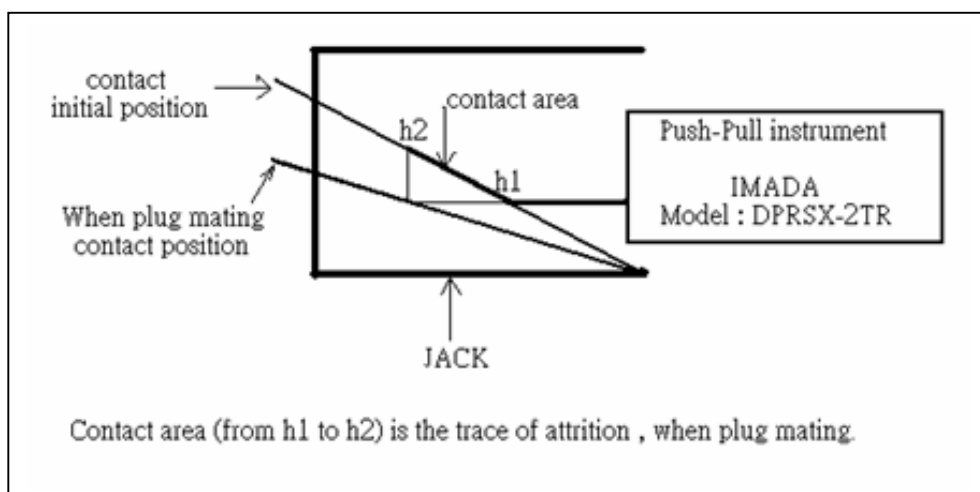


Fig 2